

HCS300FH170A2C1

1700V/300A Half Bridge SiC MOSFET Module

Description

The HCS300FH170A2C1 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips and SiC Diode designed for applications such as the Motor drives and Renewable energy.



Features

- Blocking Voltage: 1700V
- $R_{ds(on)}=6.4m\Omega$
- Low Thermal Resistance with Si3N4 AMB
- 175°C Maximum Junction Temperature
- 62mm Half Bridge Module

Applications

- Motor Drives
- Solar and Wind Inverter Systems
- Vehicle Fast Chargers
- UPS

Circuit Diagram

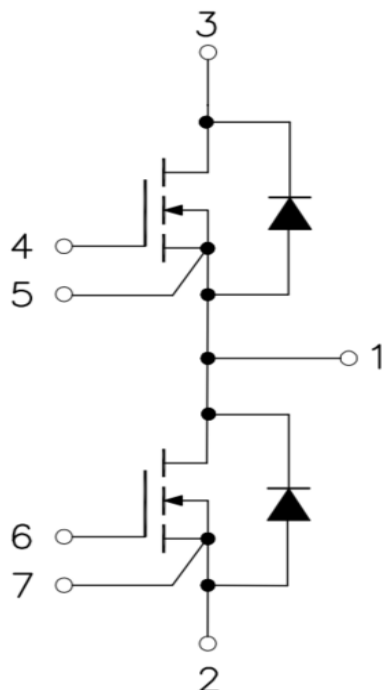


Figure 1. Out Drawing & Circuit Diagram HCS300FH170A2C1

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Pin Configuration and Marking Information

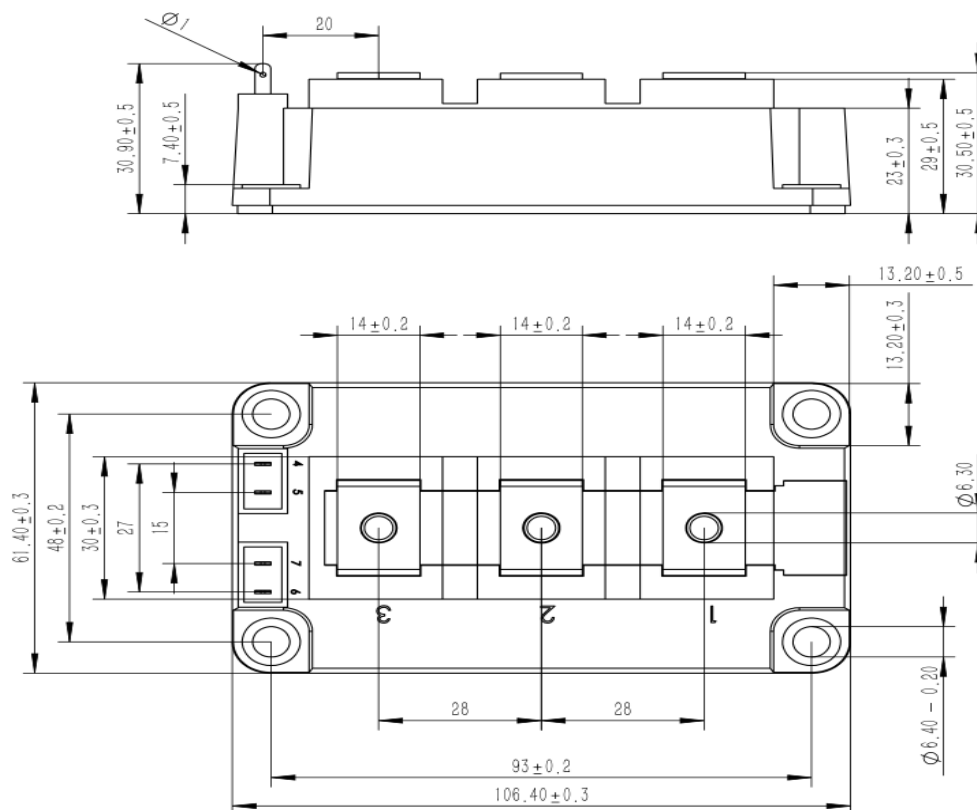


Figure 2. Pin Configuration

Module

Parameter	Conditions	Value	Unit
Isolation voltage	RMS, f =0Hz, t =1min	4.0	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 10	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>400	-
Module lead resistance, terminals – chip	Tc=25°C	0.6	mΩ
Mounting torque for module mounting	M6	4 to 6	Nm
Weight	-	320	g

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Maximum Ratings ($T_j=25^{\circ}\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Conditions	Value	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1700	V
V_{GS}	Gate-Source Voltage	D-S Short, AC frequency 1Hz, Note1	-10 to 22	V
I_{DS}	DC Continuous Drain Current	$T_c=25^{\circ}\text{C}$, $V_{GS}=+15\text{V}$	380	A
I_{DS}	DC Continuous Drain Current	$T_c=80^{\circ}\text{C}$, $V_{GS}=+15\text{V}$	300	A
I_{SD}	Source-Drain Current (Diode)	$T_c=25^{\circ}\text{C}$, with ON signal	380	A
I_{SD}	Source-Drain Current (Diode)	$T_c=80^{\circ}\text{C}$, with ON signal	300	A
I_{DSM}	Pulse Drain Current	$T_c=65^{\circ}\text{C}$, Pulse Width=1ms, $V_{GS}=+15\text{V}$, Note 2	600	A
P_{tot}	Total Power Dissipation	$T_c=25^{\circ}\text{C}$	1578	W
T_{jmax}	Max Junction temperature	-	175	$^{\circ}\text{C}$
T_{stg}	Storage temperature	-	-40 to 125	$^{\circ}\text{C}$

Note1: Recommended Operating Value: -4V/+15V, -5V/+15V

Note2: Pulse width limited by maximum junction temperature

Diode Electrical Characteristics $T_j=25^{\circ}\text{C}$ Unless Otherwise Specified, Chip)

Symbol	Item	Conditions		Value			Unit
				Min.	Typ.	Max.	
V _F	Diode Forward Voltage	I _F =300A, V _{GS} =0V	T _j =25°C	-	1.75	-	V
			T _j =175°C	-	2.75	-	
T _{rr}	Diode Reverse Recovery Time	(Switch Side) V _{DD} =900V, I _O =300A V _{GS} =+15V/-4V R _{G(ON)} =R _{G(OFF)} =2.2Ω	T _j =25°C	-	22	-	ns
			T _j =150°C	-	34	-	
I _{RM}	Peak Reverse Recovery Current	(FRD Side) V _{RR} =900V, I _F =300A V _{GE} =+15V/-4V Inductive load Switching operation	T _j =25°C	-	57	-	A
			T _j =150°C	-	129	-	
Q _{rr}	Recovered Charge		T _j =25°C	-	0.78	-	μC
			T _j =150°C	-	2.59	-	
E _{rr}	Reverse Recovered Energy		T _j =25°C	-	0.1	-	mJ
			T _j =150°C	-	0.4	-	
R _{th(j-c)}	Thermal Resulance, Junction to Case(Diode)			-	0.068	-	°C/W

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MOSFET Electrical Characteristics ($T_j=25^{\circ}\text{C}$ Unless Otherwise Specified, Chip)

Symbol	Item	Conditions		Value			Unit
				Min.	Typ.	Max.	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =300μA		1700	-	-	V
I _{DSS}	Zero gate voltage drain current	V _{DS} =1200V, V _{GS} =0V		-	3	-	μA
V _{GS(Th)}	Gate-source threshold voltage	I _D =180mA, V _{DS} =V _{GS}	T _J =25°C	1.8	2.7	-	V
			T _J =175°C	-	1.9	-	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V, V _{DS} =0V	T _J =25°C	-	20	-	nA
R _{DS(on)} (Chip)	Static drain-source On-state resistance	I _D =300A, V _{GS} =15V	T _J =25°C	-	6.4	-	mΩ
			T _J =175°C	-	10.5	-	mΩ
V _{DS(on)} (Chip)	Static drain-source On-state resistance	I _D =300A, V _{GS} =15V	T _J =25°C	-	1.90	-	V
			T _J =175°C	-	3.1	-	V
C _{iss}	Input capacitance	V _D =1000V, V _{GS} =0V, f =1mHz, V _{AC} =25mV		-	22860	-	pF
C _{oss}	Output capacitance			-	615	-	pF
C _{rss}	Reverse transfer capacitance			-	113	-	pF
R _{Gint}	Internal ate resistor	f =1MHZ, V _{AC} =25mV		-	2.3	-	Ω
Q _g	Total gate charge	V _{DD} =1000V, I _D =240A, V _{GS} =+15/-4V		-	780	-	nC
t _{d(on)}	Turn-on delay time	V _{DD} =900V I _D =300A V _{GS} =+15/-4V R _{G(ON)} =2.2Ω R _{G(OFF)} =2.2Ω Inductive load Switching operation	T _J =25°C	-	102	-	ns
			T _J =150°C	-	96	-	
t _r	Rise time		T _J =25°C	-	59	-	ns
			T _J =150°C	-	50	-	
t _{d(off)}	Turn-off delay time		T _J =25°C	-	174	-	ns
			T _J =150°C	-	196	-	
t _f	Fall time		T _J =25°C	-	54	-	ns
			T _J =150°C	-	58	-	
E _{on}	Turn-on power dissipation		T _J =25°C	-	20.1	-	mJ
			T _J =150°C	-	16.60	-	
E _{off}	Turn-off power dissipation		T _J =25°C	-	7.4	-	mJ
			T _J =150°C	-	7.6	-	
R _{th(j-c)}	FET Thermal Resistance	Junction to Case		-	0.095	-	K/W

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Test Conditions

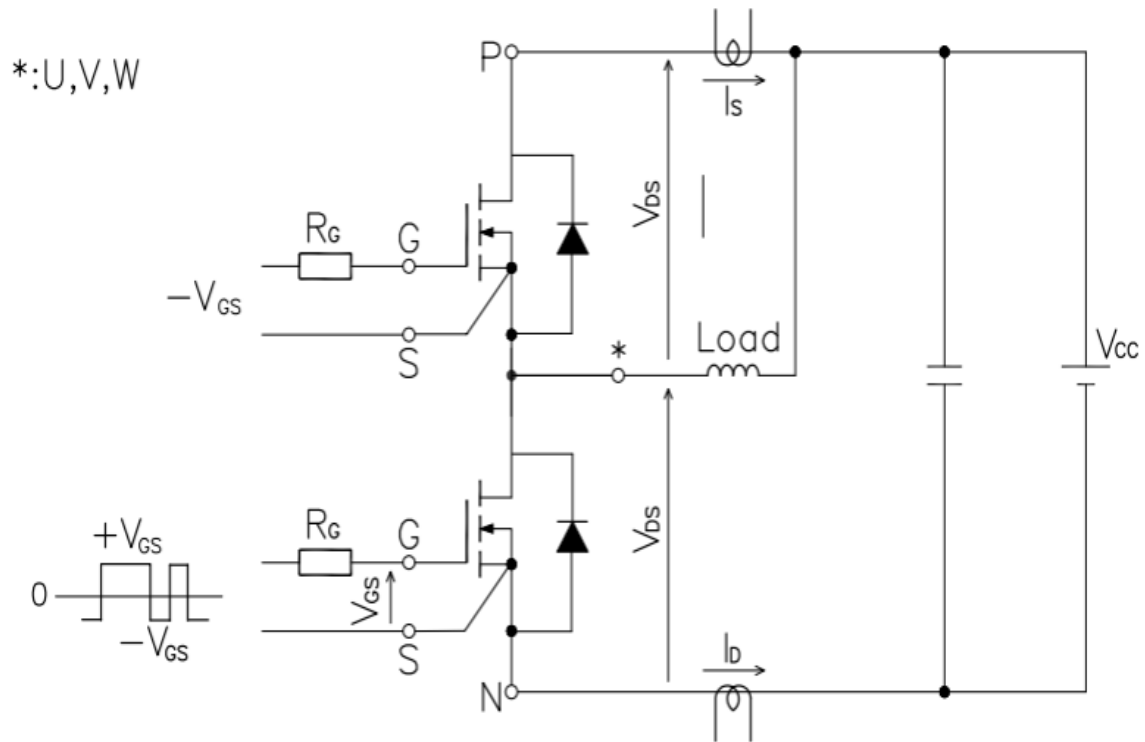


Figure 3. Switching Time Measure Circuit

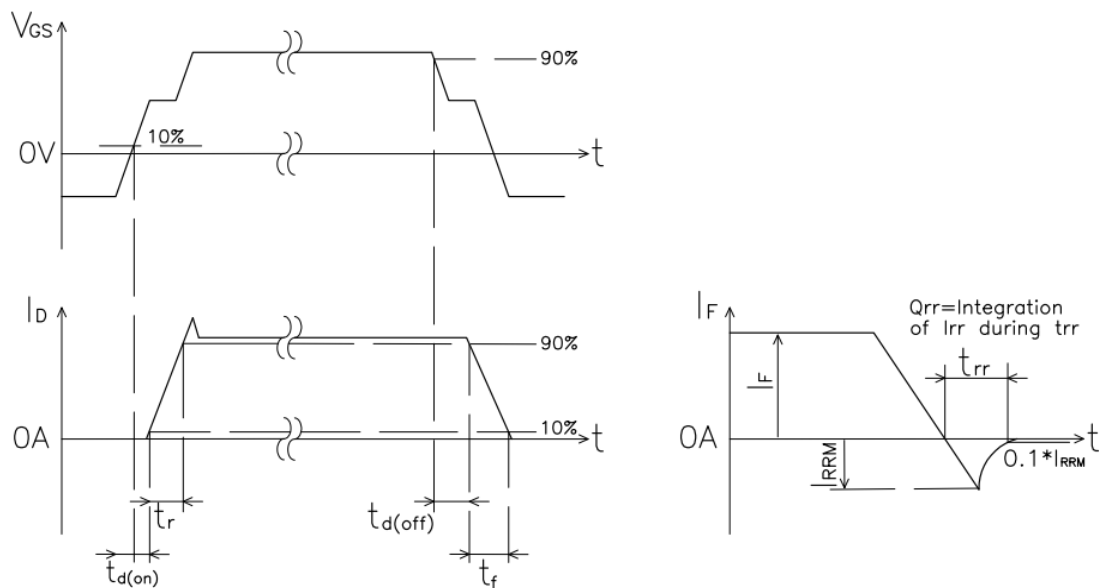


Figure 4. Switching Time Definition

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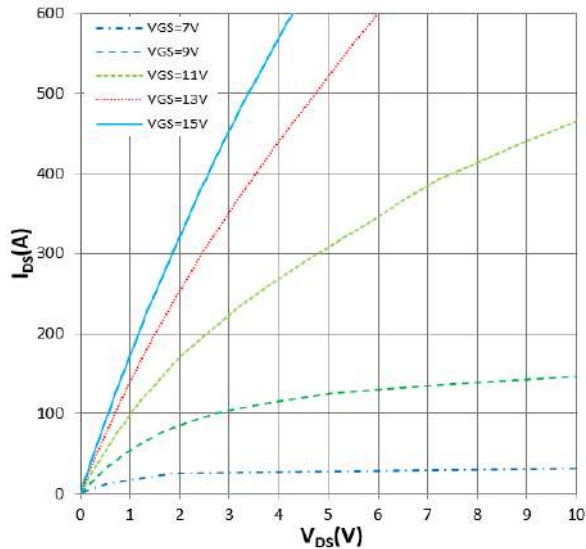


Figure 5. I_{DS} VS V_{DS}
 $T_J = 25^\circ\text{C}$

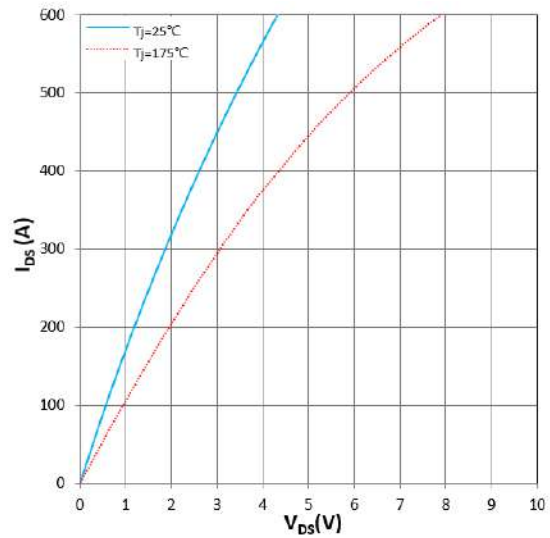


Figure 6. I_{DS} VS V_{DS}
 $V_{GS} = +15\text{V}$

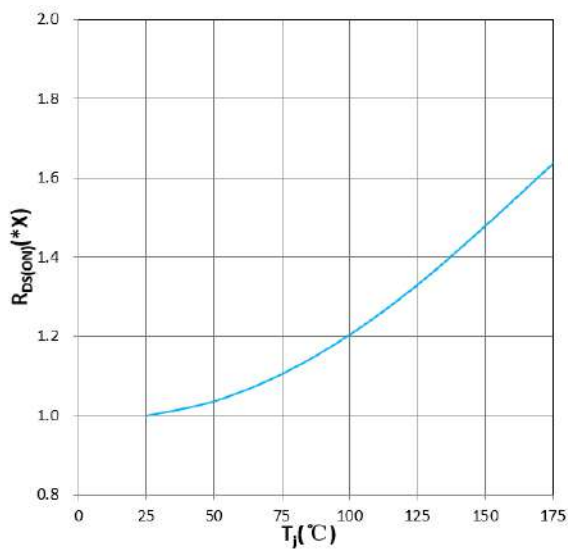


Figure 7. $R_{DS(ON)}$ VS T_J
 $V_{GS} = +15\text{V}$, $I_D = 300\text{A}$, $1.0X = 6.4\text{m}\Omega$

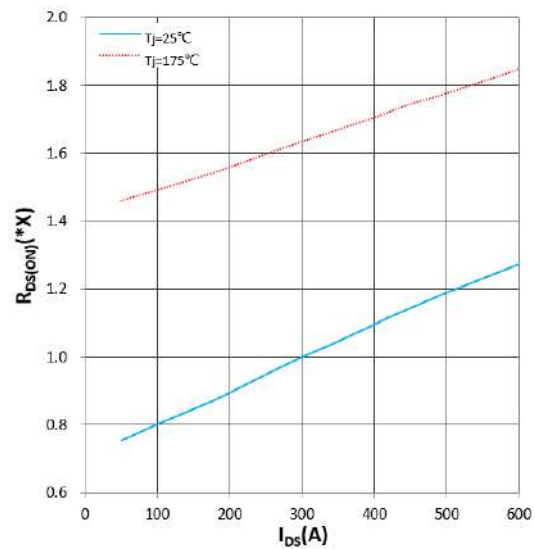


Figure 8. $R_{DS(ON)}$ VS T_J
 $V_{GS} = +15\text{V}$, $1.0X = 6.4\text{m}\Omega$

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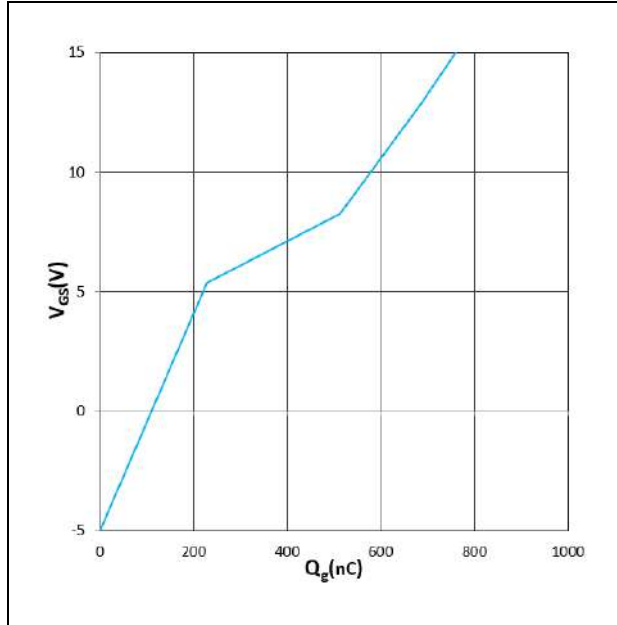


Figure 9. V_{GS} VS Q_g
 $V_{DS}=1000V$, $I_D=250A$, $T_J=25^{\circ}C$

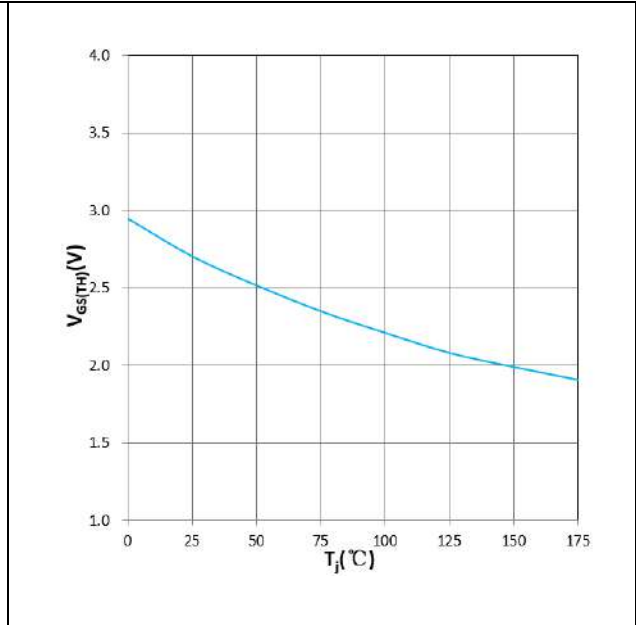


Figure 10. $V_{GS(TH)}$ VS T_J
 $V_{GS}=V_{DS}$, $I_D=180mA$

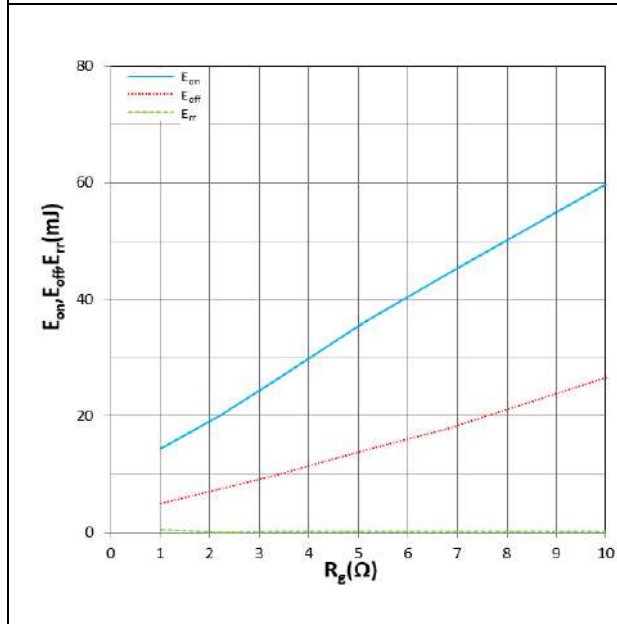


Figure 11. E_{on} , E_{off} , E_r VS R_g
 $T_J=25^{\circ}C$, $V_{DD}=900V$, $V_{GS}=+15V/-4V$, $I_D=300A$
Inductive Load

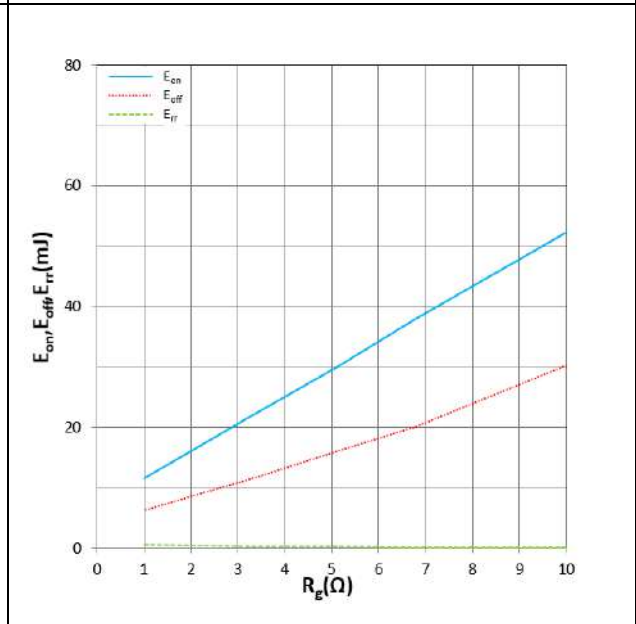


Figure 12. E_{on} , E_{off} , E_r VS R_g
 $T_J=150^{\circ}C$, $V_{DD}=900V$, $V_{GS}=+15V/-4V$, $I_D=300A$
Inductive Load

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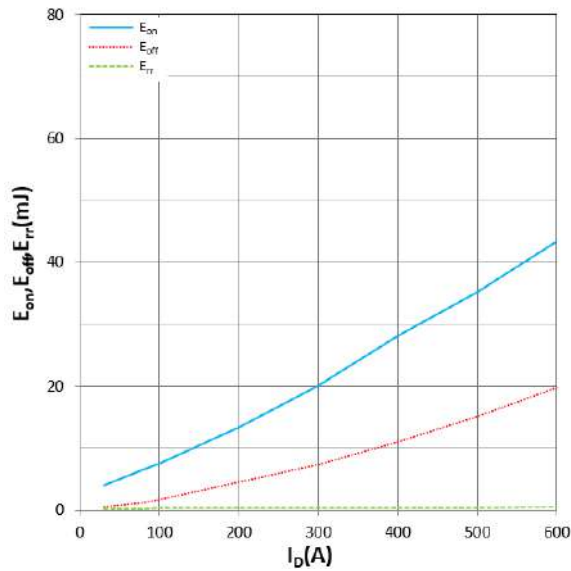


Figure 13. E_{on} , E_{off} , E_{tr} VS I_{DS}
 $T = 25^\circ\text{C}$, $V_{DD} = 900\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$
 $R_{G(ON)}/R_{G(OFF)} = 2.2/2.2\Omega$, Inductive Load

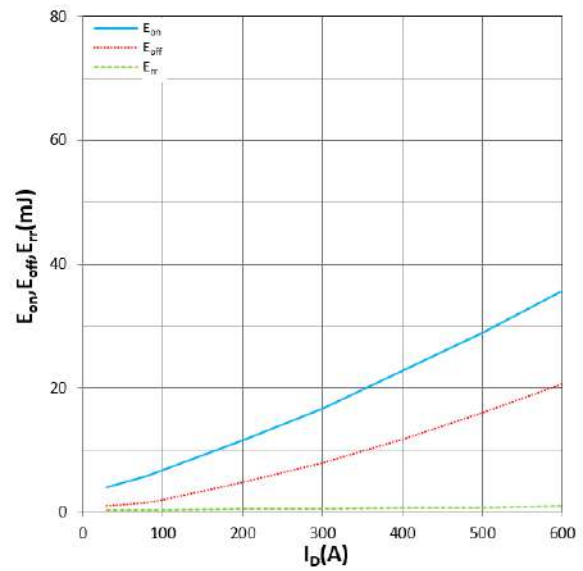


Figure 14. E_{on} , E_{off} , E_{tr} VS I_{DS}
 $T = 150^\circ\text{C}$, $V_{DD} = 900\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$
 $R_{G(ON)}/R_{G(OFF)} = 2.2/2.2\Omega$, Inductive Load

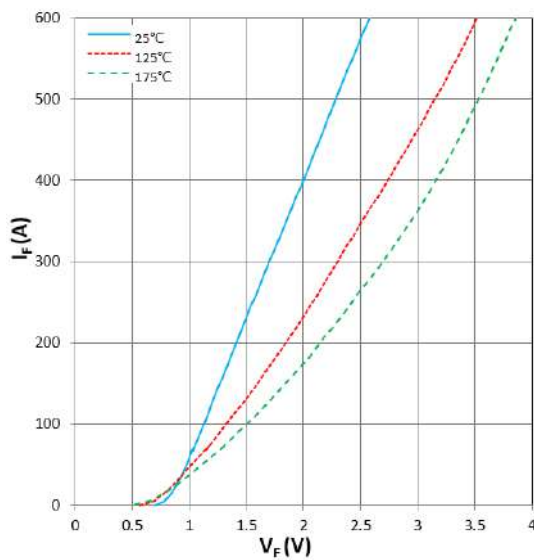


Figure 15. I_F VS V_F
 $V_{GS} = 0\text{V}$

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This product data sheet describes the characteristics of this product for which a warranty is granted.

Any such warranty is granted exclusively under the terms and conditions of the supply agreement.

There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances.

For information on the types in question, please contact the sales staff responsible for you.

Changes to this product data sheet are reserved.

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Revision History

Document Version	Description of Changes
RevX.0.1	Released

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